



**YAREN**  
TECHNOLOGY

**6N60**

**Power MOSFET**

## 5.5 Amps, 600 Volts N-CHANNEL MOSFET

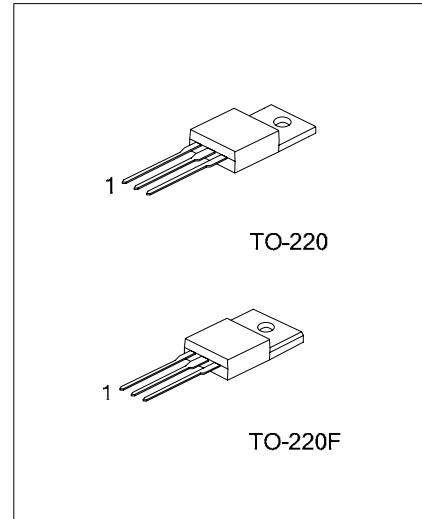
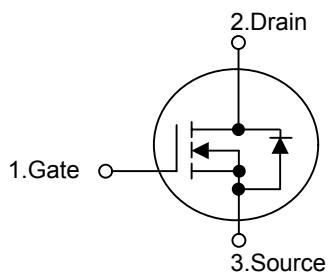
### ■ DESCRIPTION

The YR6N60 is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in switching power supplies and adaptors.

### ■ FEATURES

- \*  $R_{DS(ON)} = 2.0\Omega @ V_{GS} = 10V$
- \* Ultra low gate charge (typical 20 nC )
- \* Low reverse transfer Capacitance (  $C_{RSS} = \text{typical } 10pF$  )
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

### ■ SYMBOL



\*Pb-free plating product number: 6N60

■ ABSOLUTE MAXIMUM RATINGS ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage	6N60	$V_{DSS}$	600	V
	6N65		650	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Avalanche Current (Note 1)		$I_{AR}$	5.5	A
Continuous Drain Current	$T_c = 25^\circ\text{C}$	$I_D$	5.5	A
	$T_c = 100^\circ\text{C}$		3.0	A
Pulsed Drain Current (Note 1)		$I_{DM}$	24.8	A
Avalanche Energy	Single Pulsed (Note 2)	$E_{AS}$	440	mJ
	Repetitive (Note 1)	$E_{AR}$	13	mJ
Power Dissipation		$P_D$	62.5	W
Junction Temperature		$T_J$	+150	
Operating Temperature		$T_{OPR}$	-55 ~ +150	
Storage Temperature		$T_{STG}$	-55 ~ +150	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction-to-Ambient		$\theta_{JA}$	62	°C/W
Junction-to-Case		$\theta_{JC}$	2	°C/W

■ ELECTRICAL CHARACTERISTICS ( $T_J=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>							
Drain-Source Breakdown Voltage	6N60	$BV_{DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	600			V
	6N65			650			V
Drain-Source Leakage Current		$I_{DSS}$	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$			10	$\mu\text{A}$
Gate- Source Leakage Current	Forward	$I_{GSS}$	$V_{GS} = 20\text{V}, V_{DS} = 0\text{V}$			100	nA
	Reverse		$V_{GS} = -20\text{V}, V_{DS} = 0\text{V}$			-100	nA
Breakdown Voltage Temperature Coefficient		$BV_{DSS}/T_J$	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$		0.53		V/
<b>ON CHARACTERISTICS</b>							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0		4.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{V}, I_D = 2.75\text{A}$		1.7	2.0	$\Omega$
<b>DYNAMIC CHARACTERISTICS</b>							
Input Capacitance		$C_{ISS}$	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1.0 \text{ MHz}$		770	1000	pF
Output Capacitance		$C_{OSS}$			95	120	pF
Reverse Transfer Capacitance		$C_{RSS}$			10	13	pF
<b>SWITCHING CHARACTERISTICS</b>							
Turn-On Delay Time		$t_{D(ON)}$	$V_{DD}=300\text{V}, I_D = 5.5\text{A}, R_G = 25\Omega$ (Note 4, 5)		20	50	ns
Turn-On Rise Time		$t_R$			70	150	ns
Turn-Off Delay Time		$t_{D(OFF)}$			40	90	ns
Turn-Off Fall Time		$t_F$			45	100	ns
Total Gate Charge		$Q_G$	$V_{DS}=480\text{V}, I_D=5.5\text{A}, V_{GS}=10 \text{ V}$ (Note 4, 5)		20	25	nC
Gate-Source Charge		$Q_{GS}$			4.9		nC
Gate-Drain Charge		$Q_{GD}$			9.4		nC

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### ■ ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0 \text{ V}$ , $I_S = 5.5 \text{ A}$			1.4	V
Maximum Continuous Drain-Source Diode Forward Current	$I_S$				5.5	A
Maximum Pulsed Drain-Source Diode Forward Current	$I_{SM}$				24.8	A
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0 \text{ V}$ , $I_S = 6.0 \text{ A}$ ,		290		ns
Reverse Recovery Charge	$Q_{RR}$	$ dI_F/dt  = 100 \text{ A}/\mu\text{s}$ (Note 4)	2.35			$\mu\text{C}$

- Notes:
1. Repetitive Rating : Pulse width limited by  $T_J$
  2.  $L = 16.8\text{mH}$ ,  $I_{AS} = 5.5\text{A}$ ,  $\Delta V = 90\text{V}$ ,  $R_G = 25 \Omega$ , Starting  $T_J = 25^\circ\text{C}$
  3.  $I_{SD} \leq 5.5\text{A}$ ,  $dI/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
  4. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
  5. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

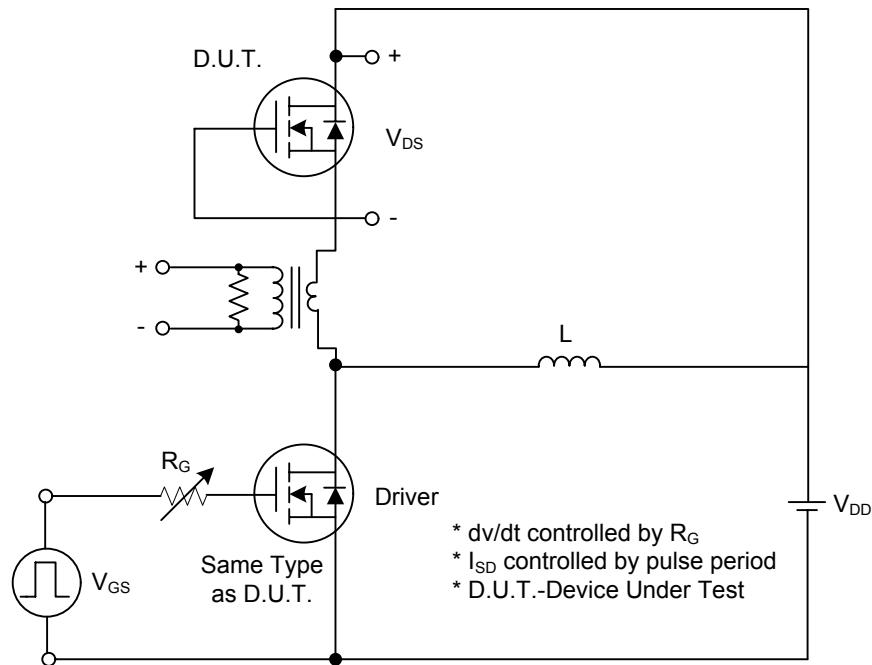


Fig. 1A Peak Diode Recovery dv/dt Test Circuit

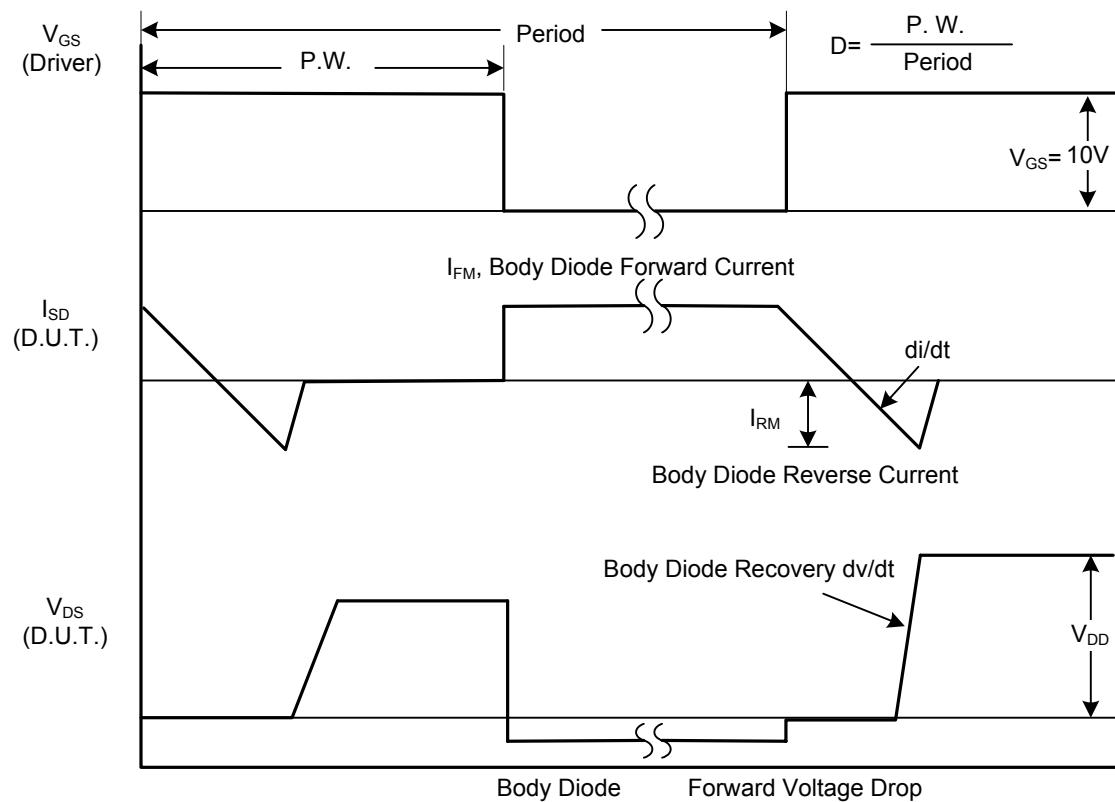
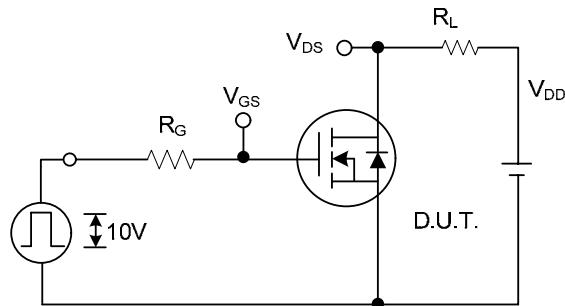
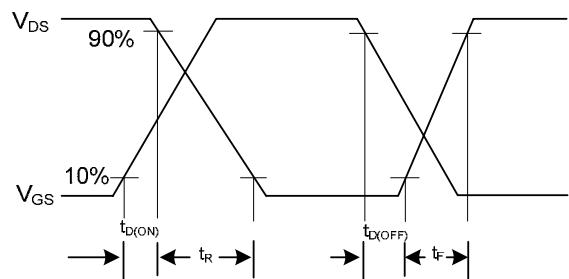


Fig. 1B Peak Diode Recovery dv/dt Waveforms

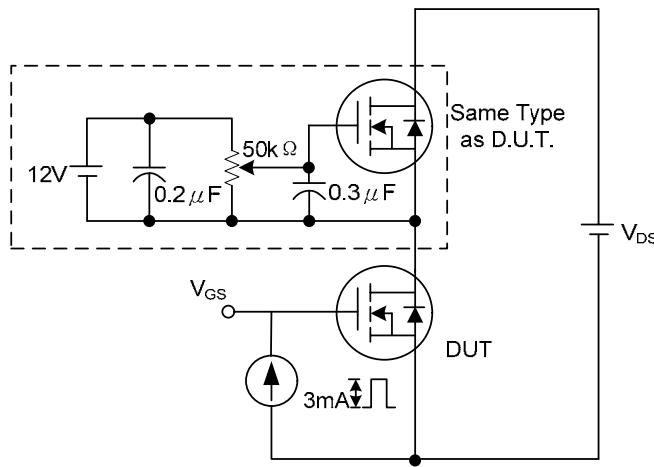
## ■ TEST CIRCUITS AND WAVEFORMS (Cont.)



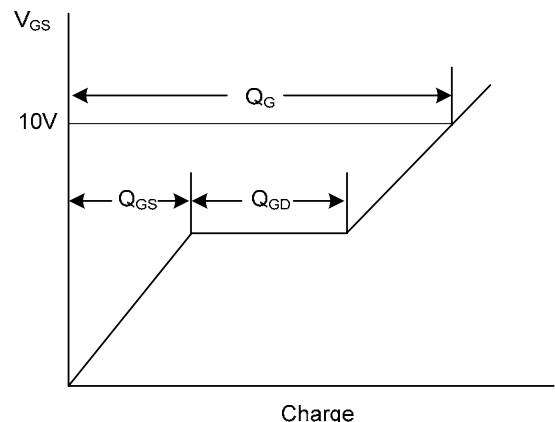
**Fig. 2A** Switching Test Circuit



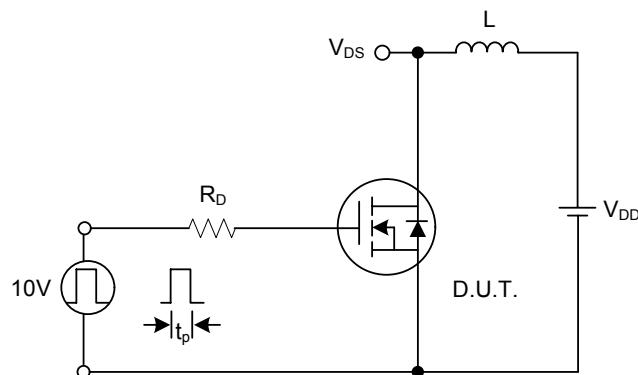
**Fig. 2B** Switching Waveforms



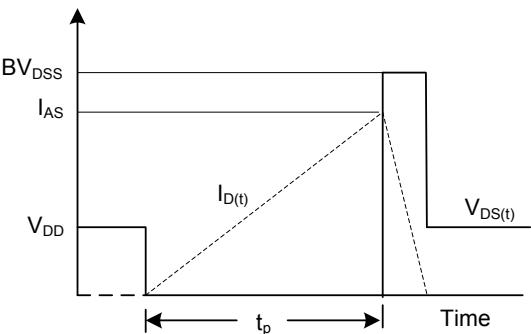
**Fig. 3A** Gate Charge Test Circuit



**Fig. 3B** Gate Charge Waveform



**Fig. 4A** Unclamped Inductive Switching Test Circuit



**Fig. 4B** Unclamped Inductive Switching Waveforms